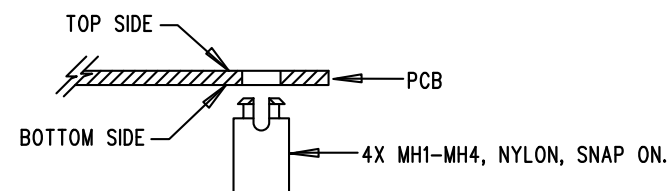
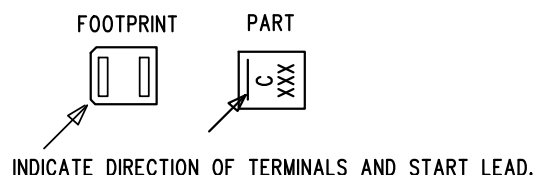


NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AS SHOWN BELOW:



8. INSTALL INDUCTOR L1 AS SHOWN BELOW:



ANALOG DEVICES			
TITLE: TOP ASSEMBLY DRAWING 42V, 3.5A SYNCHRONOUS STEP-DOWN REGULATOR WITH 2.5uA QUIESCENT CURRENT			
SIZE N/A	IC NO. LT8615RUDM EVAL-LT8615-AZ	REV. 2	
FILENAME:			SHT 1 OF 2